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EXAMINER'S INITIALS	PATENT NO.	DATE	1	NAME	CLASS	SUBCLASS	FILING	
	4,796,194	01/03/89	Atherton				08/20/	
	5,089,970	02/18/92	Lee et al.				10/05/	
	5,108,570	04/28/92	Wang				03/30/	
-	5,220,517	06/15/93	Sierk et al.				08/31/	
	5,236,868	08/17/93	Nulman				04/20/	90
ç	5,260,868	11/09/93	Gupta et al.				10/15/	91
	5,295,242	03/15/94	Mashruwala et	al. HE	CEIV	ED	11/02/	90
	5,309,221	05/03/94	Fischer et al.	ΔΙ_	N 2 1 2	003	12/31/	91
	5,329,463	07/12/94	Sierk et al.				01/13/	
	5,367,624	11/22/94	Cooper	lechno	ogy Cent o	r 2100	06/11/	93
	5,398,336	03/14/95	Tantry et al.				06/16/	93
	5,402,367	03/28/95	Sullivan et al.				07/19/	93
	5,408,405	04/18/95	Mozumder et al				09/20/	93
	5,410,473	04/25/95	Kaneko et al.				12/16/	92
		FOR	EIGN PATENT	DOCUMENTS				
EXAMINER'S	DATENTANO.	DATE	60	UNTRY	CLASS	SUBCLASS	Trans	lation
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	01-283934	11/15/89	Japan				X	
	2,050,247	08/29/91	Canada				X	
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-				an. "Dielectric CMP		Process Contr	ol Base	d on
				lova Measuring Instr		esing Technolo	my " =	- 10
			. 1990. "Semicon on-Wesley Publis	ductor Integrated Cir hing Company.	CHIL Proce	ssing recnnoic	ogy. p	g. 48.
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EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS	FILING	DATE
	5,490,097	02/06/96	Swenson et al	•	1		08/06/	93
	5,495,417	02/27/96	Fuduka et al.				03/16/	93
	5,497,316	03/05/96	Sierk et al.				04/04/	95
	5,503,707	04/02/96	Maung et al.				09722/	93
,	5,508,947	-04/16/96	Sierk et al.				05/13/	94-
	5,629,216	05/13/97	Wijaranakula	et al.			-02/27/	96
~	5,657,254	08/12/97	Sierk et al.				-04/15/	96
	5,661,669	08/26/97	Mozumder et	al	ECEIV	ED	106/07/	95
-	5,694,325	12/02/97	Fukuda et al.		AN 217	nna -	-11/22/	95
	5,698,989	12/16/97	Nulman				09/13/	96
	5,719,495	02/17/98	Moslehi	IEGNA	Ogy Cent	er 2100	06/05/	96
	-5,740,429	04/14/98	Wang et al.				07/07/	
	5,751,582	05/12/98	Saxena et al.				09/24/	96
,	5,754,297	05/19/98	Nulman			-	04/14/	97
	5,764,543	-06/09/98	Kennedy				06/16/	95
		FORI	EIGN PATEN	T DOCUMENTS				
EXAMINER'S INITIALS	PATENT NO.	DATE		COUNTRY	CLASS	SUBCLASS	Trans	lation
1,111,125		<i>D.D</i>	`		0255	00002.100	Yes	No
	2,165,847	08/29/91	Canada				X	
-, -	2,194,855	08/29/91	Canada				X	
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-				egrated Circuit Manı	ıfacturing. _İ	op. 464-498 Sa	ın Dieg	ο,
	California: Acade			Shah 1991 <i>CEPT</i> -	-A Compute	or-Aided Manu	facturin	
-				ty and Availability in				_
	York, New York:	IEEE.		-				
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EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS	FILING	DATE
	5,808,303	09/15/98	Schlagheck et a	ł. –			01/29/9)7
	5,838,595	11/17/98	Sullivan et al				11/25/9	96
	5,883,437	03/16/99	Maruyama et al	•			12/28/9)5
	5.910,011	06/08/99	Cruse				05/12/9)7
	6,054,379	04/25/00	Yau et al.				02/11/9	18
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EXAMINER'S INITIALS	PATENT NO.	DATE	CO	UNTRY	CLASS	SUBCLASS	Trans	lation No
	05-151231	06/18/93	Japan			,		X
	05-216896	08/27/93	Japan					X
	05-266029	10/15/93	Japan	RI	ECEIV	FD .		X
	06-110894	04/22/94	Japan					X
	06-176994	06/24/94	Japan	J/	N 21	003		X
	06-252236	09/09/94	Japan	Techno	logy Cent	er 2100	—	X
	06-260380	09/16/94	Japan			100	<u> </u>	X
	08-149583	06/07/96	Japan				X	
	09-34535	02/07/97	Japan				X	
	EP 0877308 A2	11/11/98	Europe				Х	
	11-67853	03/09/99	Japan				X	-
	-1072967A3	11/21/01	Europe				X	
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				Telfeyan. 1995. "A al of Vacuum Science				nch
			•	logy Manufacturing				
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				for Display Techno				
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	09/363,966	07/29/99	Arackaparambil	Compu	ter Integrated Manufactu	ring Techniques		
•		1715	et al.					
	09/469,227	12/22/99	Somekh et al.		Fool Control System, Met	thed and	-	
	00/610 044	07/10/00	37	Mediu	m and Method of Exporting	a or Importing		
	09/619,044	07/19/00	Yuan		Data in a Manufacturing			
				System		2/toution		
	09/637,620	08/11/00	Chi et al:		e Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispate	ching Component for Ass	ociating ·		
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								Yes No
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	Zhou, Zhen-F	long and R	afael Reif. August	t 1995.	"Epi-Film Thickness Mea	asurements Using	Emission	Fourier
	Transform In	frared Spec	troscopy—Part II:	Real-Ti	ime in Situ Process Monit	toring and Contro	l." IEEE	
	Transactions	on Semicor	ductor Manufactu	ring, Vo	ol. 8, No. 3.			
					ry, James Pugmire, Scott			
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	American Va			,, IVIII	poilo, milliocom. 42	- autonai ojinpe		
				, D. Bor	ning, J. Chung, K. Chang,	G. Ray, D. Brad	bury, O. S	. 1
	Nakagawa, S	Oh. and D	Bartelink, Decer	mber 19	95. "Using a Statistical N	Aetrology Frame	work to Id	entify
			Sources of Die- ar national Electron I		r-level ILD Thickness Va Meeting.	riation in CMP F	rocesses.'	,
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	09/655,542	09/06/00	Yuan		Method and Medium for Defi				
					to Transform an Application I e for a Service	arogram		-	
	09/725,908	11/30/00	Chi et al.		c Subject Information General	ion in			-
					e Services of Distributed Obje	ct Systems			
	09/800,980	03/08/01	Hawkins et al:	Dynami	e and Extensible Task Guide	-,			
	09/811,667	03/20/01	Yuan et al.		olerant and Automated Compu	ter .			
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	February 199 Speciality Co	6. "On-Lin	e Integrated Met I st International C	rology fo CMP Plan	Schraub, D. Trojan, 4 th Stamb r CMP Processing." Santa Cla parization Conference.	ara, Californi	a: VMIC		
	CMP Pad We	Duane Borea r Using R	ning, James Moyi un by Run Feedb	ne, Arnor ack Cont	n Hurwitz, and John Curry. Ju rol." Santa Clara, California:	ne 1996. "C VLSI Multile	ompensatevel Inter	ing f	for ect
	Conference.	ne William	Movne Taber St	mith Iam	nes Moyne, Roland Telfeyan, A	Arnon Hurwit	tz. Scott		
•	Shellman, and	l John Tayl	or. October 199 0	5. "Run l	by Run Control of Chemical-N			TEE	EE
	SEMI [1986]	(C), Vol. I	9, No. 4, pp. 307	1-314. tion and I	Measurement of Equipment Re	liability. Av	ailability.	and	
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	Manufacturing	." Advance	ed Micro Devises,	TWM	CC.	Control			
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	and Possibilitie	es." Autom	atica, Vol. 36, pp.	. 1567-	·1603, 2000. ully Automated Chemical-Me	chanical Dia	narization	Proc	ese "
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	Sokol, and Ta	run Parikh.	November 1998	"Mult	izone Uniformity Control of	CMP Proce	ess Utilizi	ng a I	Pre
	and Post-Meas	surement St	rategy." Seattle, V	Washin	gton: SEMETECH Symposiu		_		-
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	www.consiliun	n.com/prodi	ucts/fab300_page.h	ıtm#F	FAB300 Introduction					
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			ting of the Electroc		cal Society.					
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					and Michael Lacy. April					/
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	Research Soci			•	10 0 10		·	(T' 1 T)		
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EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS		
	4,698,766	10/06/87	Entwistle et al.				05/17/	<u> </u>
	4,967.381	10/30/90	Lane et al.				07/06/	
<u></u>	5,208,765	05/04/93	Turnbull				07/20/	90
,	5,226,118	07/06/93	Daker et al.				01/29/	91
	5,231,585	07/27/93	Kobayashi et al				06/20/	90
	5,420,796	05/30/95	Weling et al.				12/23/	93
	5,469,361	11/21/95	Moyne				06/06/	94
	-5,525,808	06/11/96	Irie et al.		 -		12/20/	94
	5,586,039	12/17/96	Hirsch et al.				02/27/	95
•	5,603,707	02/18/97	Trombetta et al				11/28/	95
	5,664,987	09/09/97	Renteln				09/04/	96
	5,812,407	09/22/98	Sato et al.				08/12/	97
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EXAMINER'S INITIALS	PATENT NO.	DATE	CO	DUNTRY	CLASS	SUBCLASS	Trans	lation No
	61-171147	08/01/86	Japan					X_
-	6-184434	07/05/94	Japan				 	X
	0 621 522 A2	10/26/94	Europe				X	
	8-50161	02/20/96	Japan				<u> </u>	X
	8-304023	11/22/96	Japan					X
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EXAMINER'S INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS	FILING	DATE
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	5,870,306	02/09/99	Harada				06/13/	97
<u></u>	5,903.455	05/11/99	Sharpe, Jr. et al				12/12/	96
	5,916,016	06/29/99	Bothra				10/23/	97
che	5,923,553	07/13/99	Yi				10/05/	96
	5,930,138	07/27/99	Lin et al.				09/10/	97
	5,940,300	08/17/99	Ozaki-				05/08/	97
	5,960,214	09/28/99	Sharpe, Ir. et al				12/04/	96
	5,963,881	10/05/99	Kahn et al.		 		10/20/	97
	5,982,920	11/09/99	Tobin, Ir. et al.				01/08/	97
	6,041,270	03/21/00	Steffan et al.	•			12/05/	97
	6,078,845	06/20/00	Friedman				11/25/	96
	6,112,130	08/29/00	Fukuda et al.				10/01/	97
	6,148,246	11/14/00	Kawazome		-		06/10/	98
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EXAMINER'S	PATENT NO.	DATE	CC	DUNTRY	CLASS	SUBCLASS	Transl	ation
INITIALS						9 9	Yes	No
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	10-173029	06/26/98	Japan					X
	0 895 145 A1	02/03/99	Europe		-		X	T Y
	11-126816	05/11/99	Japan					X
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Nicholas A. WARD et al.

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Nicholas A. WARD et al.

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